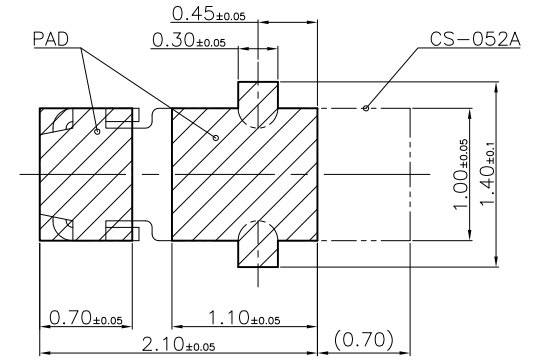
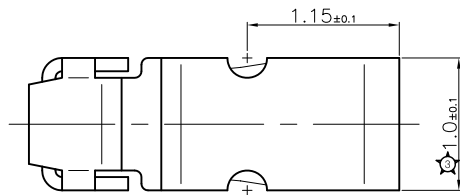
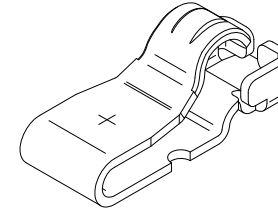
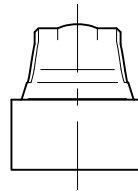
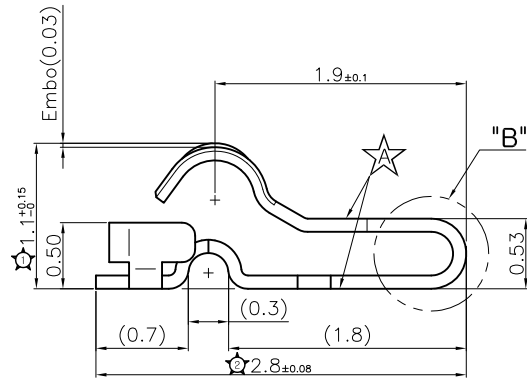


SIMULATION

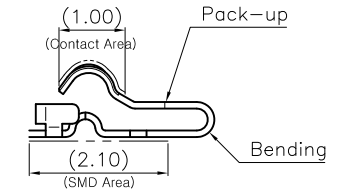


RECOMMENDED PCB LAYOUT(Top View)



***NOTE**

1. PLATING
 - Contact Area : Au 0.1μm Min over Ni 1.5~4.0μm.
 - SMD Area : Au 0.05 μm Min over Ni 1.50~4.0μm.
 - Bending & Pick-up : Ni 1.5~3.5μm.
2. ☆: C.T.Q
3. ☆: 평탄도 0.05 Max.
4. Contact 가동거리 : 0.6mm
권장 Contact 높이 : 가동거리의 60~80% 범위 내 (0.36~0.48mm) => (0.62~0.74mm)
* CONTACT 가동거리(Max)는 0.6mm 이상으로 한다.
5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.



1	Contact	Ti-Cu	Note.1	t0.1
No	Part name	Material	Finish	Remarks
General Tolerance		Scale N/S	Units mm	Sheet
Dimension	mm (°)	Date	2014. 02. 04	1 of 1
X	± 0.2	Drawn	Design	Checked
X.X	± 0.15	J.S. Kim	2014/02/04	Reviewed
X.XX	± 0.1			Approved
X.XXX	± 0.05			
ANGLE	± 2°			
		협진커넥터(주) HYUPJIN CONNECTOR, Co.,Ltd.		TITLE
				CS-052A Contact
				Customer Drawing
				SW No.
				DWG No. CS-052A-A1
				Rev. 0